IN THE CLAIMS:

Claims 3 through 12 were cancelled by the Examiner's Amendment. Claims 1, 13, 14, 16, 17 and 18 have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Currently amended) A method for electrically testing a flip-chip semiconductor assembly formed from at least one integrated circuit (IC) die and a substrate, the method comprising:

directly detachably contacting a surface of the substrate with probes;

while the substrate is in contact with the probes, bringing the at least one IC die ~~and the substrate~~ together in conductive contact to form the flip-chip semiconductor assembly; and

before the at least one IC die is sealed, electrically testing the assembly using the probes.

2. (Previously presented) The method of claim 1, wherein contacting the substrate with the probes comprises contacting the substrate with the probes at a die-attach station.

3.-12. (Cancelled)

13. (Currently amended) The method of claim 1, wherein ~~the act of~~ bringing the at least one IC die and the substrate together comprises pressing the at least one IC die against a surface of the substrate so bond pads on a surface of the at least one IC die are in a curable conductive contact with conductive pads on the surface of the substrate.

14. (Currently amended) The method of ~~claim 1,~~ claim 13, further comprising placing conductive epoxy dots on one of the bond pads on the at least one IC die and the conductive pads on the substrate.

15. (Previously presented) The method of claim 14, wherein the conductive epoxy dots comprise one of dry conductive epoxy dots and wet conductive epoxy dots.

16. (Currently amended) The method of claim 1, wherein ~~the act of~~ bringing the at least one IC die and the substrate together comprises flip-chip attaching the at least one IC die to the substrate.

17. (Currently amended) The method of claim 1, further comprising reworking the flip-chip semiconductor assembly and retesting the flip-chip semiconductor assembly if the flip-chip semiconductor assembly ~~fails the~~ fails electrical testing ~~act~~.

18. (Currently amended) The method of claim 1, further comprising curing the ~~curable~~ conductive contact if the flip-chip semiconductor assembly ~~passes the~~ passes electrical testing ~~act~~.